CLAIMS

1. A sheet for sealing a hollow electronic device comprising thermoplastic resin, satisfying at least one of (a) to (d) below:

(a) after a sheet for sealing a hollow electronic device having a weight of 5 g is immersed in 50 ml of ion exchange water and then left at 121°C and 2 atmospheric pressure for 20 hours, the ion exchange water has a chloride ion concentration of less than 30 ppm on a mass basis;

(b) after a sheet for sealing a hollow electronic device having a weight of 5 g is immersed in 50 ml of ion exchange water and then left at 121°C and 2 atmospheric pressure for 20 hours, the ion exchange water has a sodium ion concentration of less than 10 ppm on a mass basis;

(c) after a sheet for sealing a hollow electronic device having a weight of 5 g is immersed in 50 ml of ion exchange water and then left at 121°C and 2 atmospheric pressure for 20 hours, the ion exchange water has a phosphate ion concentration of less than 30 ppm on a mass basis; and

(d) after a sheet for sealing a hollow electronic device having a weight of 5 g is immersed in 50 ml of ion exchange water and then left at 121°C and 2 atmospheric pressure for 20 hours, the ion exchange water has a sulfate ion concentration of less than 5 ppm on a mass basis,

wherein the sheet for sealing a hollow type electronic device has a moisture permeability of 500 g/m^2·24 hours or less after thermal curing when a thickness of the sheet is

made to be 250 μm under a condition of a temperature of 85°C, a humidity of 85%, and a duration of 168 hours.

2. The sheet for sealing a hollow type electronic device according to claim 1, wherein the sheet for sealing a hollow type electronic device contains 70 to 90% by volume of an inorganic filler to the entire sheet for sealing a hollow type electronic device.

3. The sheet for sealing a hollow type electronic device according to any one of claim 1 or 2, wherein the sheet for sealing a hollow type electronic device contains an ion scavenger.

4. The sheet for sealing a hollow type electronic device according to claim 3, wherein the ion scavenger is a hydrotalcites-based compound.

5. A method of manufacturing a hollow type electronic device package comprising:

a laminating step of laminating the resin sheet for sealing a hollow type electronic device according to any one of claims 1 to 4 on a hollow type electronic device so that the resin sheet covers one or a plurality of the hollow type electronic devices that are mounted on a substrate; and

a sealing body forming step of curing the resin sheet for sealing a hollow type electronic device to form a sealing body.